

DZ2708200L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2S082 in SSSMini2 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: JJ

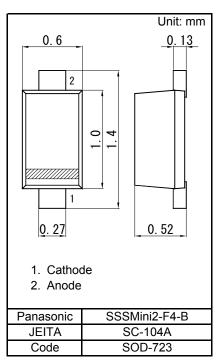
Packaging

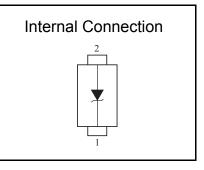
Embossed type (Thermo-compression sealing) : 10 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C							
Parameter	Symbol	Rating	Unit				
Repetitive peak forward current	IFRM	200	mA				
Total power dissipation *1	PT	120	mW				
Electrostatic discharge *2	ESD	±8	kV				
Junction temperature	Tj	150	°C				
Operating ambient temperature	Topr	-40 to +85	С°				
Storage temperature	Tstg	-55 to +150	С°				

Storage temperatureTstg-55 to +150Note)*1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)Solder in (0.4 mm x 0.3 mm)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)





■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 10 mA			1.0	V	
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	7.79		8.61	V	
Zener operating resistance	RZ	IZ = 5 mA			20	Ω	
Zener rise operating resistance	RZK	IZ = 0.5 mA			60	Ω	
Reverse current	IR	VR = 5.0 V			0.1	μA	
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		4.7		mV/°C	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25°C for VZ mesurement.

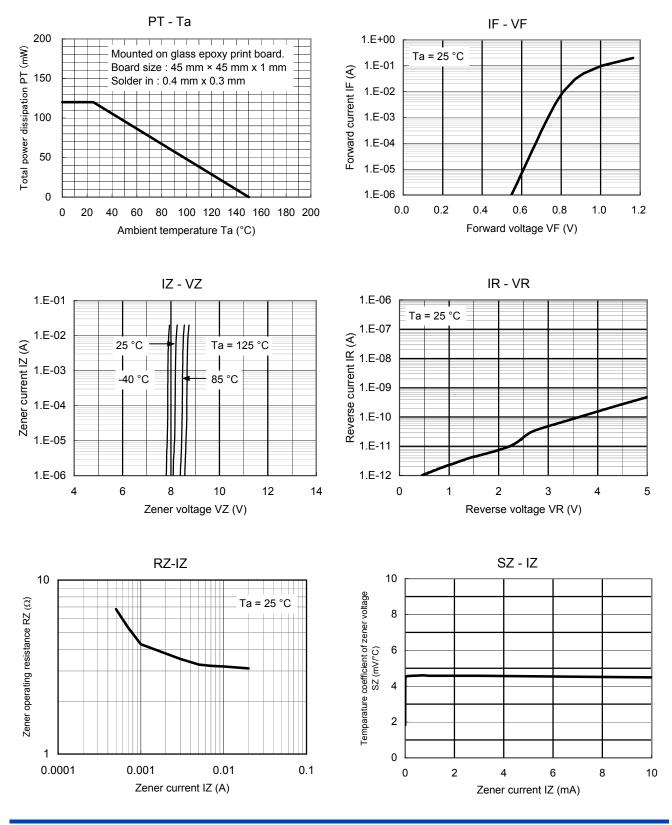
VZ value measured at other temperature must be adjusted to VZ (25°C)

*2 VZ guaranted 20 ms after current flow.

*3 Tj = 25°C to 150°C



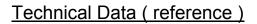
Technical Data (reference)

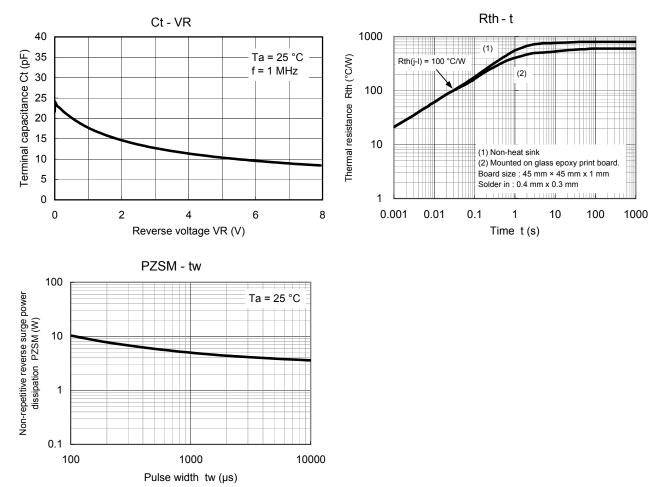


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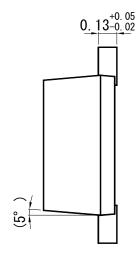


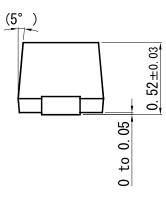


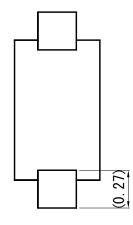


SSSMini2-F4-B

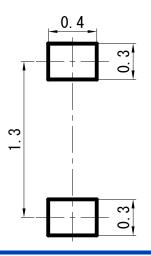
0. 60±0.05 2 2 90 0 0 1 0. 27-0.03 0 27-0.03











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Unit: mm

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